

# Wen-Hsi Lee

## List of Publications by Year in descending order

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41  
times ranked

309  
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#	ARTICLE	IF	CITATIONS
1	Fabrication of Vertically Stacked Nanosheet Junctionless Field-Effect Transistors and Applications for the CMOS and CFET Inverters. IEEE Transactions on Electron Devices, 2020, 67, 3504-3509.	3.0	29
2	A Study of Trimethylsilane (3MS) and Tetramethylsilane (4MS) Based $\hat{\pm}$ -SiCN:H/ $\hat{\pm}$ -SiCO:H Diffusion Barrier Films. Materials, 2012, 5, 377-384.	2.9	17
3	Influence of SiO <sub>2</sub> Addition on the Dielectric Properties and Microstructure of (Ba <sub>0.96</sub> Ca <sub>0.04</sub> )(Ti <sub>0.85</sub> Zr <sub>0.15</sub> )O <sub>3</sub> Ceramics. International Journal of Applied Ceramic Technology, 2009, 6, 692-701.	2.1	14
4	Contrasting conduction mechanisms of two internal barrier layer capacitors: (Mn, Nb)-doped SrTiO <sub>3</sub> and CaCu <sub>3</sub> Ti <sub>4</sub> O <sub>12</sub> . Journal of Applied Physics, 2017, 121, .	2.5	14
5	Characteristic of high frequency Fe-Si-Cr material for motor application by selective laser melting. AIP Advances, 2019, 9, .	1.3	14
6	Effect of microwave annealing on electrical characteristics of TiN/Al/TiN/HfO <sub>2</sub> /Si MOS capacitors. Applied Physics Letters, 2017, 111, .	3.3	12
7	Synthesis of ZnO Nanoparticles to Fabricate a Mask-Free Thin-Film Transistor by Inkjet Printing. Journal of Nanotechnology, 2012, 2012, 1-8.	3.4	11
8	Phase development and dielectric properties of BaAl <sub>2</sub> Si <sub>2</sub> O <sub>8</sub> -based low temperature co-fire ceramic material. Journal of the Ceramic Society of Japan, 2008, 116, 935-940.	1.1	10
9	Valence and electronic trap states of manganese in SrTiO <sub>3</sub> -based colossal permittivity barrier layer capacitors. RSC Advances, 2016, 6, 92127-92133.	3.6	10
10	High performance OTFTs using surface-modified nanocomposite dielectric gate insulator. Journal of Materials Science: Materials in Electronics, 2009, 20, 355-358.	2.2	9
11	Study on low temperature sintering and microwave dielectric properties of Ba <sub>2</sub> Ti <sub>9</sub> O <sub>20</sub> -based ceramics. Journal of the Ceramic Society of Japan, 2009, 117, 402-406.	1.1	9
12	First Demonstration of Heterogeneous IGZO/Si CFET Monolithic 3-D Integration With Dual Work Function Gate for Ultralow-Power SRAM and RF Applications. IEEE Transactions on Electron Devices, 2022, 69, 2101-2107.	3.0	9
13	Effect of Nanocomposite Gate-Dielectric Properties on Pentacene Microstructure and Field-Effect Transistor Characteristics. Journal of Nanoscience and Nanotechnology, 2010, 10, 762-769.	0.9	6
14	Development of Low Firing NPO Based on (Ca,Sr)(Ti,Zr)O <sub>3</sub> for Co-Firing Cu Electrode. Ferroelectrics, 2012, 435, 110-118.	0.6	6
15	A Study of Cu/CuMn Barrier for 22-nm Semiconductor Manufacturing. IEEE Transactions on Device and Materials Reliability, 2014, 14, 286-290.	2.0	6
16	High dopant activation of phosphorus in Ge crystal with high-temperature implantation and two-step microwave annealing. Applied Physics Letters, 2016, 109, .	3.3	6
17	Pentacene-Based Thin Film Transistor with Inkjet-Printed Nanocomposite High-K Dielectrics. Active and Passive Electronic Components, 2012, 2012, 1-7.	0.3	5
18	A Study on Cu Particles Coated With Nano-Silver by a Replacement Reaction Between Silver Nitrate and Copper Particles. Journal of Nanoscience and Nanotechnology, 2017, 17, 4157-4164.	0.9	4

#	ARTICLE	IF	CITATIONS
19	Improvement on Conductivity for Thick Film Aluminum Paste. Journal of Nanoscience and Nanotechnology, 2021, 21, 4726-4734.	0.9	4
20	Investigation of Barrier Property of Copper Manganese Alloy on Ruthenium. IEEE Transactions on Device and Materials Reliability, 2015, 15, 47-53.	2.0	3
21	Neutral beam and ICP etching of HKMG MOS capacitors: Observations and a plasma-induced damage model. Journal of Applied Physics, 2018, 123, 161517.	2.5	3
22	A Novel Method to Fabricate a Thick-Film Cu Electrode Fired in Air Through Printing Al Electrode and Reduction-Oxidation Substitution Reaction. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 485-492.	2.5	3
23	A Study of Back Electrode Stacked With Low Cost Reflective Layers For High-Efficiency Thin-Film Silicon Solar Cell. Journal of Solar Energy Engineering, Transactions of the ASME, 2014, 136, .	1.8	2
24	Effect of annealing conditions on dopants activation and stress conservation in silicon-germanium. AIP Advances, 2019, 9, .	1.3	2
25	Titanate coupling agent surface modification effect on the magnetic properties of iron-based alloy powder coil prepared using screen printing. Journal of Materials Science: Materials in Electronics, 2021, 32, 1800-1807.	2.2	2
26	Magnetic Properties of Iron-Based Alloy Powder Coils Prepared with Screen Printing Using High-Solid-Content Magnetic Pastes. Journal of Electronic Materials, 2021, 50, 2331-2338.	2.2	2
27	A Novel Fabricating a Thick Film Cu-Ni Alloy Resistor by Screen Printing an Al Electrode and Galvanic Replacement Reaction. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1997-2002.	2.5	2
28	Effect of Under-Layer Treatment of Ta/TaN Barrier Film on Corrosion Between Cu Seed and Ta in Chemical-Mechanical-Polishing Slurry. Journal of Nanoscience and Nanotechnology, 2010, 10, 4196-4203.	0.9	1
29	Using Chemical-Mechanical Polishing for Planarizing a High- $\kappa$ Nanocomposite Polyimide Insulator for Organic Thin Film Transistors Application. Journal of Nanoscience and Nanotechnology, 2011, 11, 1968-1975.	0.9	1
30	Investigation the Electroplating Behavior of Self Formed CuMn Barrier. Journal of Nanoscience and Nanotechnology, 2013, 13, 5800-5806.	0.9	1
31	Optimization of Parameters for TVS breakdown voltage: Design and Fabrication. , 2014, , .		1
32	Investigation of high-k/metal gate MOS capacitors annealed by microwave annealing as a post-metal annealing process. , 2016, , .		1
33	USJ formation using solid phase epitaxial regrowth and femtosecond laser anneal. , 2012, , .		0
34	Parameter optimization of PT-IGBT breakdown voltage. , 2014, , .		0
35	A Study on the Diffuse Mechanism and the Barrier Property of Copper Manganese Alloy on Tantalum. IEEE Journal of the Electron Devices Society, 2015, 3, 284-290.	2.1	0
36	Activation of high concentrations of phosphorus in germanium by two-steps microwave annealing. , 2016, , .		0

#	ARTICLE	IF	CITATIONS
37	A study on the plating and wetting ability of ruthenium-tungsten multi-layers for advanced Cu metallization. , 2016, , .		0
38	Investigation on Low Firing Copper for Front Electrode of Si-Based Solar Cell Applications. Journal of Nanoscience and Nanotechnology, 2018, 18, 2716-2722.	0.9	0
39	Influence of Plasma Ultraviolet/Vacuum Ultraviolet Irradiation Damage on Silicon Metal-Oxide-Semiconductor Capacitor During Etching. Journal of Nanoscience and Nanotechnology, 2021, 21, 2163-2173.	0.9	0
40	Improvement on Conductivity for Thick Film Aluminum Paste. Journal of Nanoscience and Nanotechnology, 2021, 21, 4596-4604.	0.9	0